

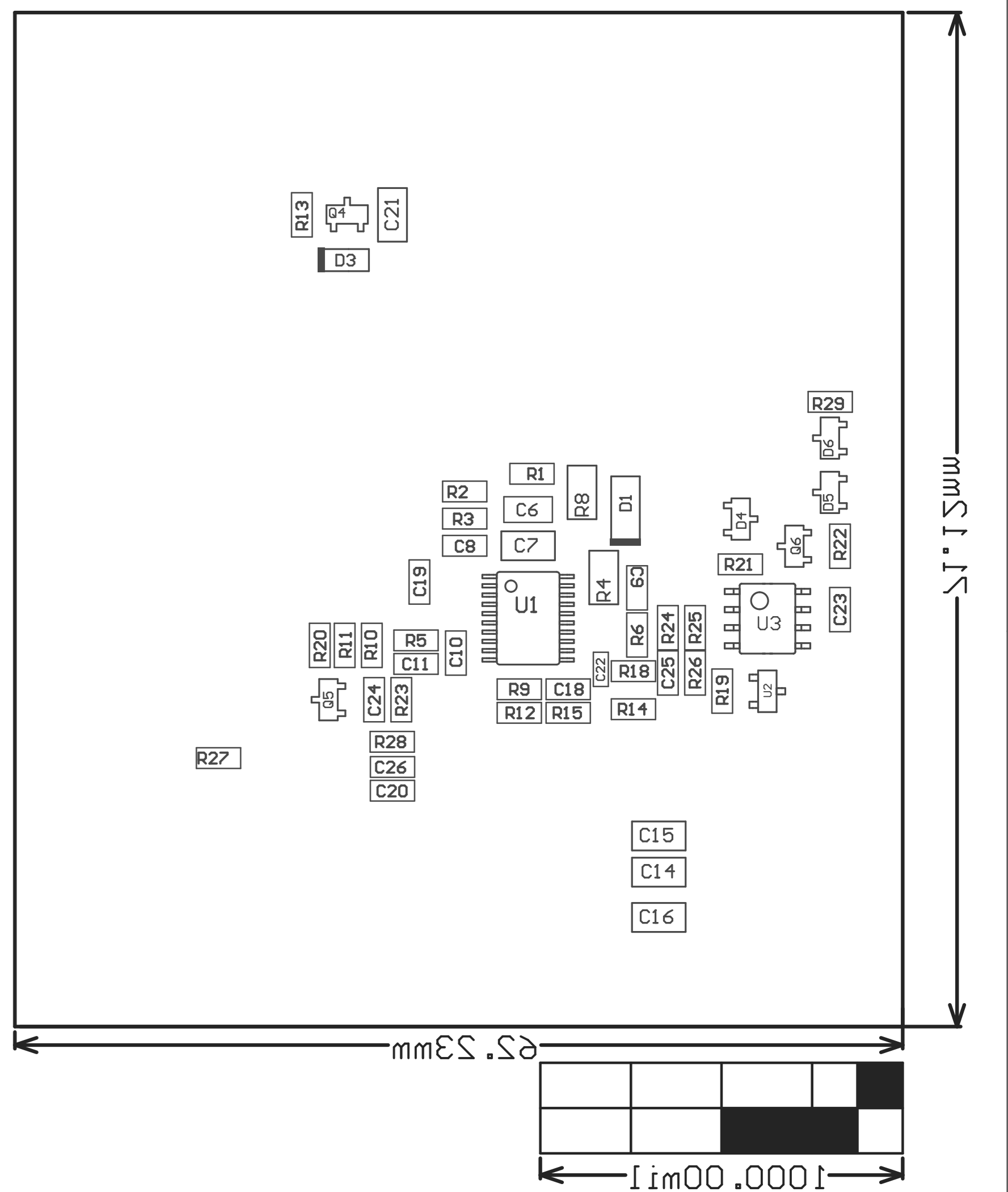
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
ASSEMBLY VARIANT: [No Variations]



PROJECT TITLE: 27U...29Uin to 24U@11A Synch. Buck with OVP	
DESIGNED FOR: Public Release	
FILE NAME: PMP30189 Rev_B PCB.PcbDoc	
ENGINEER: R. Scibilia	LAYOUT BY: R. Scibilia
SCALE: 1.00	ALTIUM DESIGNER VERSION: 17.1.5.472

BOARD #: PMP30189	REV: B	SUN REV: Not In VersionControl
TID #:		
PLOT NAME = Top Layer Assembly Drawing	GENERATED : 11/6/2017 4:32:20 PM	TEXAS INSTRUMENTS

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COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: [No Variations]

PROJECT TITLE: ZVU...Zavin to Z4UG11A Synch. Buck with OVP	
DESIGNED FOR: Public Release	
FILE NAME: PMP30189 Rev_B_PCB.PcbDoc	
LAYOUT BY: R. Scidilia	ENGINEER: R. Scidilia
ALTIM DESIGNER VERSION: 12.1.2.422	SCALE: 1.00

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PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP30189	REV: B	
	TID #:		
PLOT NAME = Bottom Layer Assembly Drawing	GENERATED : 11/6/2017	4:32:21 PM	TEXAS INSTRUMENTS

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